

**SPECIFICATIONS**

Current Rating : 3 Amp Max

Insulator resistance :

5000 M ohms Min at 1000V DC

Dielectric withstand Voltage :

1000V AC R.M.S for 1 Mintue

Operating Temperature : -55° ~ +105°C

**MATERIAL :**

Housing :P.B.T (UL 94V-0), Black

Terminal : t=0.40mm Copper Alloy, Gold Plating


**ORDER INFORMATION:**

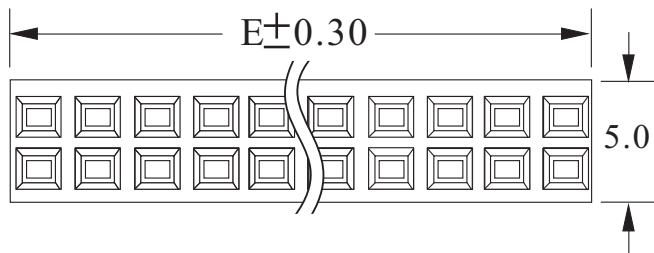
HFD1 - XX 4 - X0 - X - XX - X  
           a    b    c      d    e    f    g

- a. Pin of numbers: 04 ~ 80      b. Pastic Thick : 4: 8.5mm
- c. Plated selection:  
 0 : Tin plated  
 1 : Gold flash  
 2 : 5u" Gold on Contact Area  
 3 : 15u" Gold on Contact Area  
 4 : 30u" Gold on Contact Area  
 5 : Duplex Gold Flash on Contact Area  
 6 : Duplex 5u" Gold on Contact Area  
 7 : Duplex 15u" Gold on Contact Area  
 8 : Duplex 30u" Gold on Contact Area  
 9 : 10u" Gold on Contact Area
- d. Solder Pin length :  
 1 : A=3.2mm
- e. Plastic Color :  
 B : black color
- f. Plastic material selection:  
 P : P.B.T (off料)  
 E : P.B.T (新料)
- g. Pack selection:  
 D : Disk Pack

VERSION &amp; EC DESCRIPTION

DATE	VERSION	PAGE	DESCRIPTION
2004/03/26	A	8-9	Add HFD1-XX4 Plan
2004/10/15	A	8	Revise Material & Specifiactions
2005/03/09	A	8-9	Add Pack : Disk

GENAL TOLERANCE	DRAW DATE	2004/03/26 H. D. LI	PART NO
X. ± 0.38	DESIGN	H. D. LI	HFD1-XX4-X0-X-XX-X
.X ± 0.25	CHECKED	Y. M. LU	TITLE
.XX ± 0.15	APPROVED	J. F. KANG	2.54 2xXX 母座 H=8.5 DIP 黑PBT
.XXX ± 0.10	UNIT :mm		 宏揚精密有限公司 HOJAR PRECISION CO., LTD.

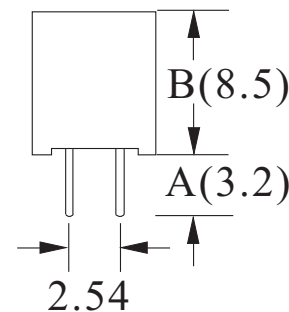
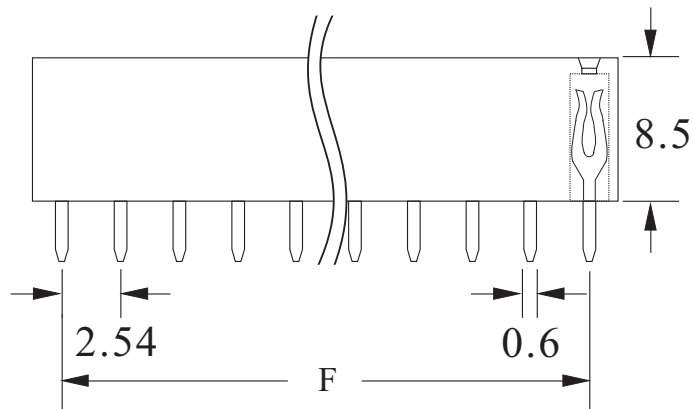


$$E = (\text{No of Posotion Per Row}) \times 2.54 + 0.5$$

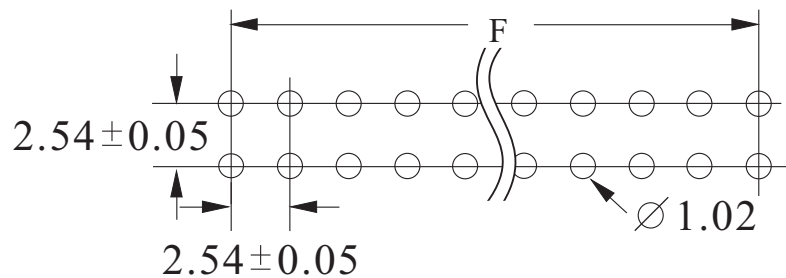
$$[(\text{No of Posotion Per Row}) \times 0.100] + 0.020$$


$$F = (\text{No of Posotion Per Row} - 1) \times 2.54$$

$$[(\text{No of Posotion Per Row} - 1) \times 0.100]$$



Recommended P.C.Board Hole Layout :



GENAL TOLERANCE	DRAW	2004/03/26	PART NO
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X. ± 0.38	DESIGN	H. D. LI	TITLE
.X ± 0.25	CHECKED	Y. M. LU	
.XX ± 0.15	APPROVED	J. F. KANG	 宏揚精密有限公司 HOJAR PRECISION CO., LTD.
.XXX ± 0.10	UNIT :mm		